

# Product Change Notification

|                     |   |             |            |               |         |
|---------------------|---|-------------|------------|---------------|---------|
| <b>Change Title</b> | Industrial Micro SD Card with flash bond pad metallization change | <b>Date</b> | 2020/08/25 | <b>PCN No</b> | F2047-1 |
| <b>PCN level:</b>   | Minor   |             |            |               |         |
| <b>Models:</b>      | Industrial Micro SD Card  |             |            |               |         |
| <b>Category:</b>    | Production  |             |            |               |         |

**Description:**

Because Micron convert the bond pad metallization of SLC NAND for wafer sales products, this PCN is being issued to address that Innodisk Industrial Micro SD Card is going to implement running change the wafer of metallization composition from Cu+ Ni/Pd (plating) to AL (Sputter). This change process has been proven to be more robust at Micron's Fab. Thus, there is no change to specification or function of Industrial Micro SD Card and the part number will not be changed.

|                              |                      |                              |
|------------------------------|----------------------|------------------------------|
| Was                          | IS                   |                              |
| Layers:                      | Layers:              | Affected DIDs:               |
| Metal 2: Cu + Ni/Pd(Plating) | Metal 2: Al(Sputter) | M72A, M73A, L73A, M68A, L72A |
| Polyimide                    | Polyimide            | M72A, M73A, L73A             |
| Non-Polyimide                | Polyimide            | M68M, L72A                   |

Source: Micron's PCN: 33273

| Model Name               | Current Part Number |
|--------------------------|---------------------|
| Industrial Micro SD Card | DS2M-02GI81AC3ST%   |
| Industrial Micro SD Card | DS2M-02GI81AW3ST%   |
| Industrial Micro SD Card | DS2M-04GI81AC3ST%   |
| Industrial Micro SD Card | DS2M-04GI81AW3ST%   |

**Key Milestone Dates**

**Effective Date:** 2020/09/04

\*Milestone dates are subject to change based on business and operational conditions.

**Customer Impact of Change and Recommended Action:**

Innodisk anticipates no negative impact to customer's application.

There is no functional implication to customer's application but improve reliability, and qualification of these changes may not be necessary.




**Notes:**

No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones.

Innodisk apologizes for any inconvenience caused by this and appreciate your understanding.

Innodisk promises that new items deliver quality and reliability for your application. If you have any further inquiry of our products or if you have any question about the specification of it, please contact Innodisk sales person.

Thank you for your confidence in Innodisk in the past and looking forward to serving you in the near future.

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